Please replace the paragraph starting at page 8, line 7 with the following paragraph:

A few additional steps/operations might be done in Step A to improve the via conductor bonding performance. For example, the adhesive layer 31 may be based on aluminum deposition wherein the aluminum is used as a sacrificial layer. Then, after the insulating via rings 32 have been formed, the exposed aluminum is coated with a thin layer of gold and possibly a subsequent nickel layer to improve bondability and aging characteristics.

IN THE CLAIMS

Please amend the claims as set forth below. In accordance with 37 C.F.R. 1.121(c)(ii), Attachment B contains the marked up version indicating all the changes made.

1. (Amended) An electrical component package comprising a base to accommodate one or more electrical components on its surface and one or more coaxial vias formed in the base, wherein each of the coaxial vias and the base form a substantially flat surface for input/output of electrical signals from the electrical component.

3. (Amended) The package of Claim 2, further comprising one or more coaxial wires, each wire connecting a site on said component to one of the one or more coaxial vias.

4. (Amended) The package of Claim 3, wherein each of the one or more coaxial wires further comprises a conductive bonding wire, a conformal coating of insulating material that surrounds the conductive bonding wire and a conductive layer that coats the coating of insulating material to form a coaxial structure.

10. (Amended) The package of claim 1, wherein the base further comprises a material having a thermal expansion coefficient that matches with thermal expansion coefficient of the one or more electrical components to be mounted on the base.

13. (Amended) A structure comprising an electrical device having at least one conductive pad, a base material to which the electrical device is mounted wherein the base has at

least one coaxial via that forms a substantially flat surface with the base, and a micro-coaxial wire connecting said pad to a conductor in said coaxial via to provide a coaxial signal path from the electrical device to the coaxial via.

21. (Amended) The structure of claim 13, wherein the base further comprises a material having a thermal expansion coefficient that matches with thermal expansion coefficient of the one or more electrical components to be mounted on the base.

22. (Amended) The structure of Claim 15 further comprising a conductive coating applied to the outside of the insulating material wherein said conductive coating is electrically attached to a shield side of said coaxial via.

33. (New) The structure of Claim 2 wherein the central conductive contact area having a first diameter is electrically coupled to a conductive layer having a second diameter larger than the first diameter, wherein the ratio of the first and second diameters depend on the desired impedance characteristic.

34. (New) The structure of Claim 2 further comprising a conductive layer, the conductive layer electrically coupled to the central conductive contact area and a part of the insulating material ring that is adjacent to the central conductive contact area.